

08-27-2003

Express Mail Label: EV306258312US



orney Docket: N1085-00191

To the Honorable Commissioner of Patents and Trademark

Documents or copy thereof.

102535639

1. Name of conveying party(ies)

- 1) Yi-Hsun Wu
- 2) Jian-Hsing Lee

8-20-03

2. Name and address of receiving party(ies):

Name: Taiwan Semiconductor Manufacturing Co. Ltd.

Internal Address:

Street Address: No. 8 Li-Hsin Road 6
Science-Based Industrial Park
Hsin-Chu, Taiwan, 300-77, R.O.C.

Additional name(s) of conveying party(ies) attached?

() Yes (X) No

3. Nature of conveyance:

- (X) Assignment () Merger
- () Security Agreement () Change of Name
- () Other

Execution Date: August 13, 2003

Additional name(s) and address(es) attached? () Yes (x) No

03913 U.S. PTO
10/644718
08/20/03

4. Application number(s) or patent number(s):

10644718

If this document is being filed together with a new application, the execution date of the application is: August 13, 2003

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached: () Yes (x) No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William H. Murray, Esq.

Internal Address:

Street Address: Duane Morris LLP

One Liberty Place

City: Philadelphia State: PA ZIP: 19103-7396

6. Total number of applications and patents involved: (1) One

7. Total fee (37 CFR 3.41).....\$40.00

(XX) Enclosed

() Authorized to be charged to deposit account

8. Deposit account number: 04-1679

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Joseph A. Powers
Registration No. 47,006

Joseph A. Powers
Signature

August 20, 2003
Date

08/26/2003 DBYRME 00000011 10644718

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40.00 DP

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SMC 2003-0246
H1\1120194.1

PATENT
REEL: 014418 FRAME: 0527

ASSIGNMENT AND AGREEMENT

For value received, we, **Yi-Hsun Wu and Jian-Hsing Lee**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **CIRCUIT AND METHOD FOR ESD PROTECTION** described in an application for Letters Patent of the United States executed on even date herewith, and all the rights and privileges in said application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

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[TSMC2003-0246]**

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Dated: 8/13/2003

Yi-Hsun Wu
Yi-Hsun Wu

Residence:

Dated: Aug. 13, 03

Jian-Hsing Lee
Jian-Hsing Lee

Residence:

PH1118195.1